

MECHANICAL CASE OUTLINE

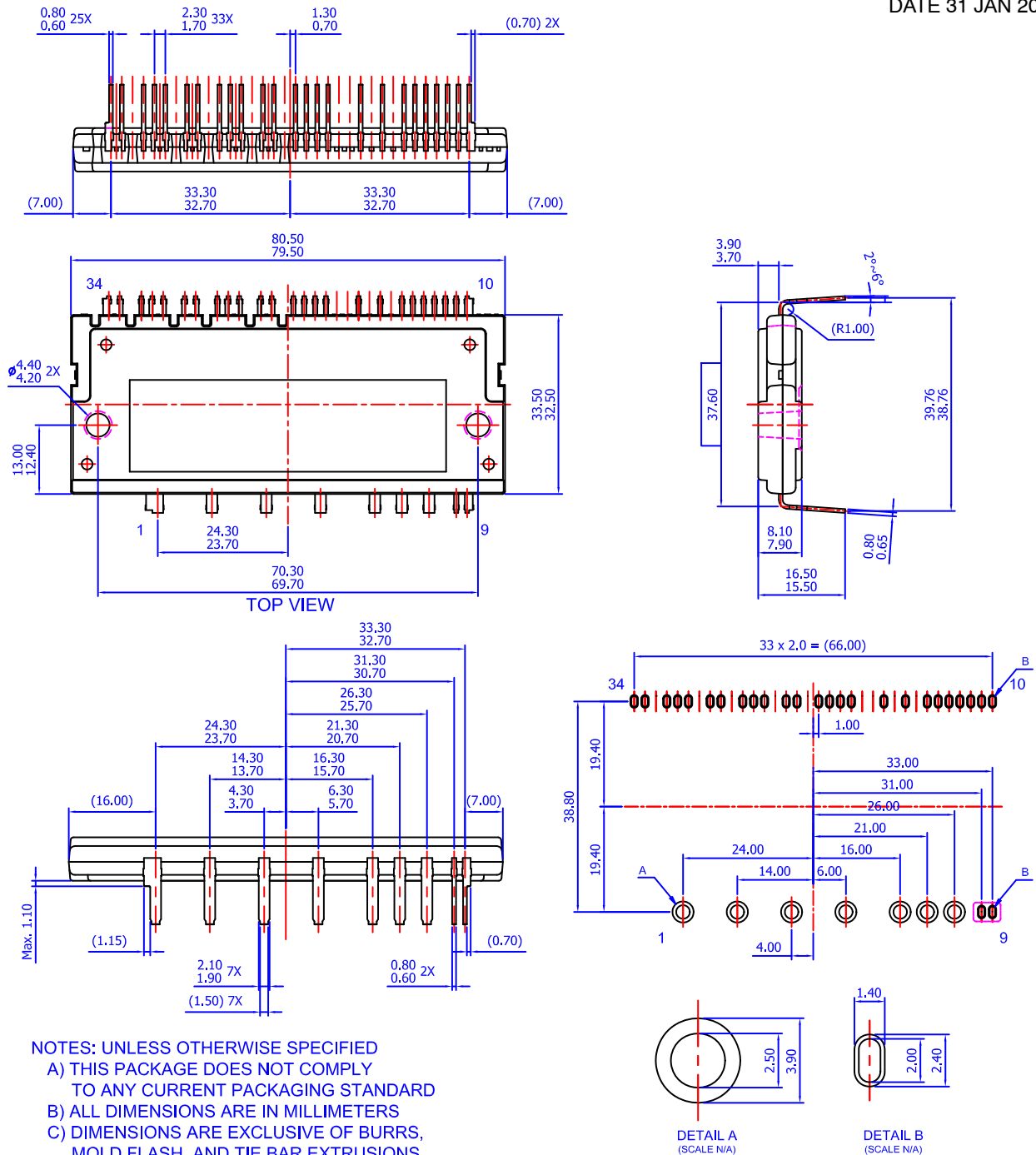
PACKAGE DIMENSIONS

ON Semiconductor®



SPMCA-A34 / 34LD, PDD STD, DBC DIP TYPE CASE MODFQ ISSUE O

DATE 31 JAN 2017



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
 - B) ALL DIMENSIONS ARE IN MILLIMETERS
 - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
 - D) PACKAGE SURFACE VOID SHALL NOT EXCEED 2.3 x 2.3 x 1.0mm
 - E) () IS REFERENCE

LAND PATTERN RECOMMENDATIONS

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